4,194,304-words × 1-bit High Speed Static Random Access Memory

# HITACHI

ADE-203-086G(Z) Rev. 8 Aug. 28, 1996

#### **Features**

- 4194304-words × 1 bit organization
- Directly TTL compatible input and output
- +5.0 V Single Supply
- Completely static memory
- No clock or timing strobe required
- Super fast access time: 15/20 ns (Max)
- Revolutional Pin Arrangement

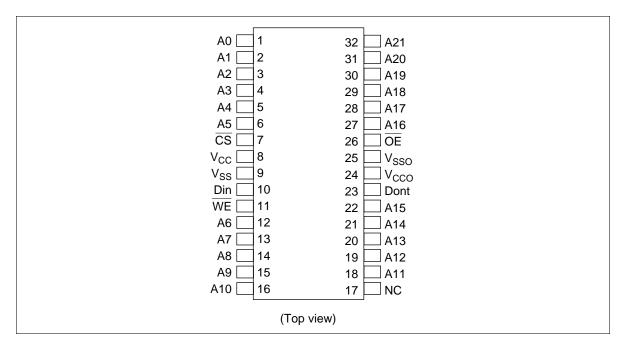
### **Ordering Information**

Type No.	Organization	Access time	Package
HM671400HJP-15		15 ns	400 mil 32 pin
HM671400HJP-20	4M × 1	20 ns	Plastic SOJ (CP-32DB)

Preliminary: This document contains information on a new product. Specifications and information contained herein are subject to change without notice.



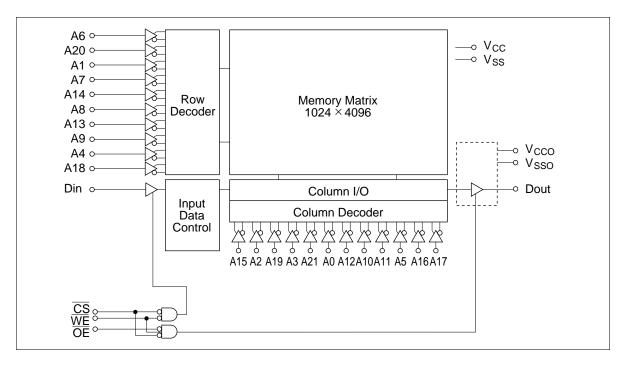
### **Pin Arrangement**



### **Pin Description**

Pin Name	Function
A0 to A21	Address Input
Din	Data Input
Dout	Data Output
WE	Write Enable
CS	Chip Select
ŌĒ	Output Enable
V <sub>cc</sub>	+5 V Power Supply
V <sub>cco</sub>	Output Buffer Power Supply
$V_{\rm SSO}$	Output Buffer Ground
V <sub>SS</sub>	Ground
NC	Not Connect

### **Block Diagram**



### **Function Table**

CS	WE	OE	Mode	Output	V <sub>cc</sub> Current
Н	Х	Х	Not Selected	High Z	I <sub>SB</sub> , I <sub>SB1</sub>
L	Н	Н	Output Disable	High Z	I <sub>CC</sub> , I <sub>CC1</sub>
L	Н	L	Read	Data Out	$I_{cc}$ , $I_{cc1}$
L	L	Н	Write	High Z	$I_{CC}$ , $I_{CC1}$
L	L	L	Write	High Z	$I_{cc}, I_{cc1}$

### **Absolute Maximum Ratings**

Item	Symbol	Rating	Unit
Supply Voltage *1	V <sub>cc</sub>	-0.5 to + 7.0	V
Voltage on any pin relative to V <sub>SS</sub> *1	V <sub>T</sub>	$-0.5$ to $V_{cc} + 0.5$	V
Power dissipation	P <sub>T</sub>	1.0/1.5 *2	W
Operating Temperature Range	Topr	0 to +70	°C
Storage Temperature Range (with bias)	Tstg (Bias)	-10 to + 85	°C
Storage Temperature Range	Tstg	-55 to + 125	°C

Notes: 1. With respect to  $V_{ss} = V_{sso}$ 

Under the dc and ac specifications shown in the Tables, this device is tested under the minimum transverse air flow exceeding 500 linear feet per minute.

### **Recommended DC Operating Conditions** $(0^{\circ}C \le Ta \le 70^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit
Supply Voltage	$V_{cc}, V_{cco}$	4.5	5.0	5.5	V
	$V_{SS}$ , $V_{SSO}$	0.0	0.0	0.0	V
Input High Voltage	$V_{IH}$	2.2	_	$V_{cc}$ + 0.5	V
Input Low Voltage	$V_{\text{IL}}$	-0.5	_	0.8	V

<sup>2.</sup>  $P_T = 1.5 \text{ W}$  is guaranteed under the minimum air flow exceeding 500 linear feet per minute.

**DC** and Operating Characteristics ( $V_{CC} = V_{CCO} = 5.0 \text{ V} \pm 10\%, \ V_{SS} = V_{SSO} = 0 \text{ V}, \ Ta = 0 \text{ to } +70^{\circ}\text{C}$ )

				15		20	
Item	Symbol	<b>Test Conditions</b>	Min	Max	Min	Max	Unit
Input Leakage Current	II <sub>u</sub> I	$V_{CC} = 5.5 \text{ V},$ $V_{IN} = 0 \text{ V to } V_{CC}$	_	2	_	2	μΑ
Output Leakage Current	II <sub>LO</sub> I	$\overline{\text{CS}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{OE}} = \text{V}_{\text{IH}},$ $\overline{\text{WE}} = \text{V}_{\text{IL}}$ $\text{V}_{\text{OUT}} = 0 \text{ V to V}_{\text{CC}}$	_	10	_	10	μА
Operating Power Supply Current	I <sub>cc</sub>	$\overline{\text{CS}} = V_{\text{IL}}, I_{\text{OUT}} = 0 \text{ mA}$	_	120	_	120	mA
Average Operating Current	I <sub>CC1</sub>	Min. cycle, $I_{OUT} = 0 \text{ mA}$	_	170	_	150	mA
Standby Power Supply Current	I <sub>SBAC</sub>	CS = V <sub>IH</sub> Min. cycle	_	100	_	80	mA
	I <sub>SBDC</sub>	$\overline{\text{CS}} = \text{V}_{\text{IH}} \text{ All input fixed}$ and $\text{V}_{\text{IN}} = \text{V}_{\text{IH}} \text{ or } \text{V}_{\text{IL}}$	_	20	_	20	mA
	I <sub>SB1</sub>		_	10	_	10	mA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8 mA	_	0.4	_	0.4	V
Output High Voltage	$V_{OH}$	$I_{OH} = -4 \text{ mA}$	2.4	_	2.4	_	V

**AC Characteristics** ( $V_{CC} = V_{CCO} = 5.0 \text{ V} \pm 10\%$ ,  $V_{SS} = V_{SSO} = 0 \text{ V}$ ,  $Ta = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ , unless otherwise noted.)

#### Read Cycle

			15		20	
Item	Symbol	Min	Max	Min	Max	Unit
Read Cycle Time	t <sub>RC</sub>	15	_	20	_	ns
Address Access Time	t <sub>AA</sub>	_	15	_	20	ns
Chip Select Access Time	t <sub>ACS</sub>	_	15	_	20	ns
Chip Selection to Output in Low Z	t <sub>LZ</sub> *1, *2	5	_	5	_	ns
Output Enable to Output Valid	t <sub>oe</sub>	_	8	_	10	ns
Output Enable to Output in Low Z	t <sub>OLZ</sub> *1, *2	2	_	2	_	ns
Chip Deselection to Output in High Z	t <sub>HZ</sub> *1, *2	0	7	0	8	ns
Output Hold from Address Change	t <sub>oh</sub>	5	_	5	_	ns

Notes: 1. This parameter is sampled and not 100% tested.

2. Transition is measured ±200 mV from steady state voltage with specified loading in Load(B).

#### Write Cycle

		15		20			
Item	Symbol	Min	Max	Min	Max	Unit	
Write Cycle Time	t <sub>wc</sub> *1	15	_	20	_	ns	
Chip Selection to End of Write	$t_{cw}$	12	_	15	_	ns	
Address Valid to End of Write	t <sub>AW</sub>	12	_	15	_	ns	
Address Setup Time	t <sub>AS</sub>	0	_	0	_	ns	
Write Pulse Width	$t_{WP}$	12	_	15	_	ns	
Write Recovery Time	$t_{WR}$	3	_	3	_	ns	
Data Valid to End of Write	$t_{\scriptscriptstyle DW}$	8	_	10	_	ns	
Data Hold Time	$t_{\scriptscriptstyle DH}$	0	_	0	_	ns	
Write Enable to Output in High Z	$t_{wz}$ *2, *3	0	7	0	8	ns	
Output Disable to Output in High Z	t <sub>OHZ</sub> *2, *3	0	7	0	8	ns	
Output Active from End of Write	t <sub>OW</sub> *2, *3	2	_	2	_	ns	

Notes: 1. All Write Cycle timings are referenced from the last valid address to the first transitioning address.

- 2. This parameter is sampled and not 100% tested.
- 3. Transition is measured ±200 mV from steady state voltage with specified with loading Load(B).

#### **Capacitance** (Ta = 25°C, f = 1 MHz)

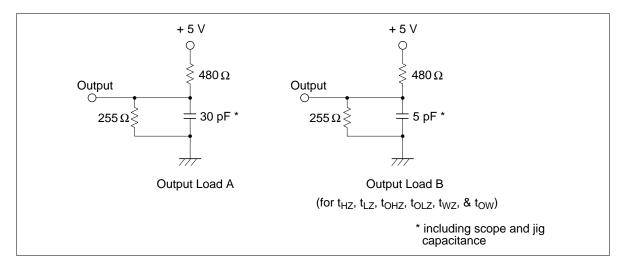
Item	Symbol	Max	Unit	<b>Test Condition</b>
Input Capacitance	C <sub>IN</sub> *1	6	pF	$V_{IN} = 0 V$
Output Capacitance	C <sub>OUT</sub> *1	8	pF	V <sub>OUT</sub> = 0 V

Note: 1. This parameter is sampled and not 100% tested.

#### **AC Test Conditions**

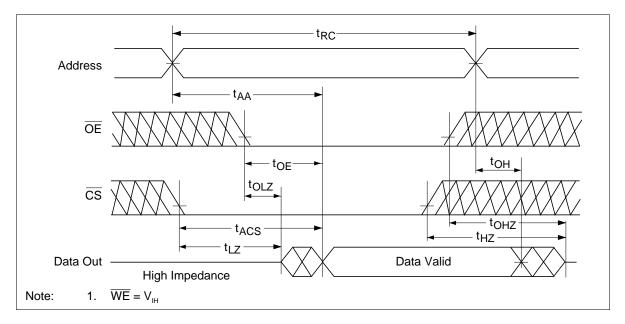
Input pulse levels: V<sub>ss</sub> to 3.0 V
 Input timing reference levels: 1.5 V

Output Load: See figure
Input rise and fall times: 4 ns
Output reference levels: 1.5 V

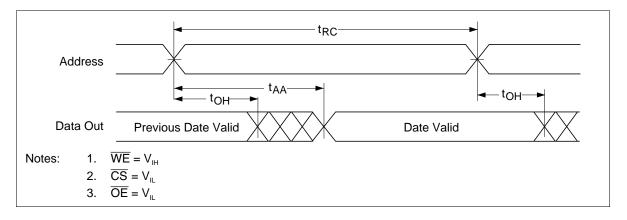


### **Timing Waveforms**

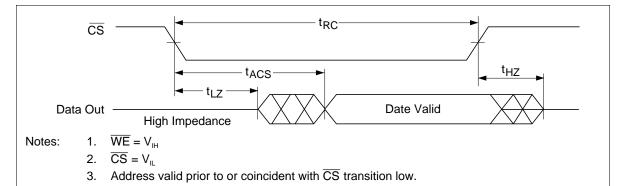
### Read Cycle-1 \*1



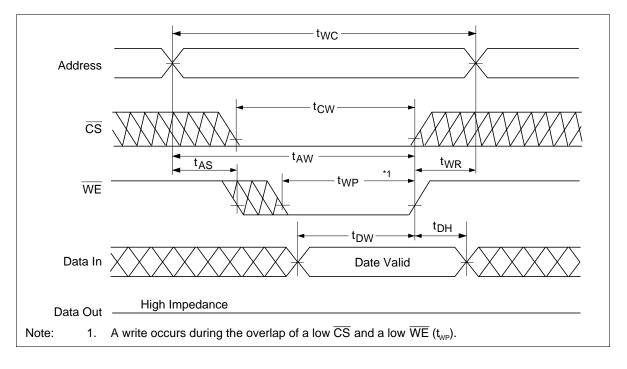
### **Read Cycle-2** \*1, \*2, \*3



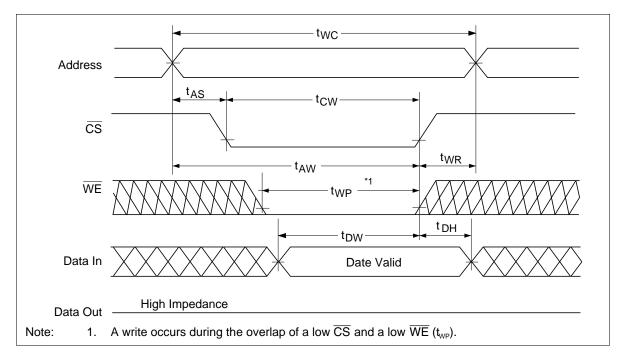
### Read Cycle-3 \*1, \*2, \*3



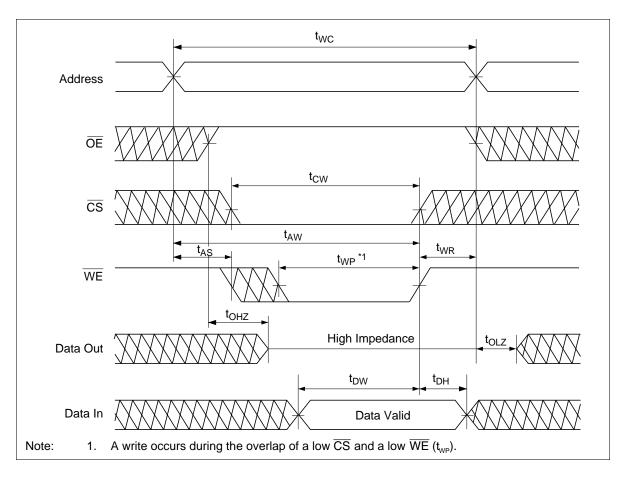
Write Cycle-1 \*1 ( $\overline{OE} = H$ ,  $\overline{WE}$  Controlled)



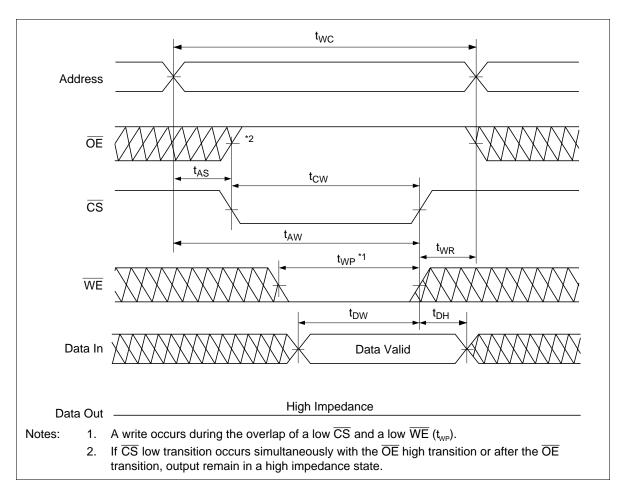
Write Cycle-2 \*1 ( $\overline{OE} = H$ ,  $\overline{CS}$  Controlled)



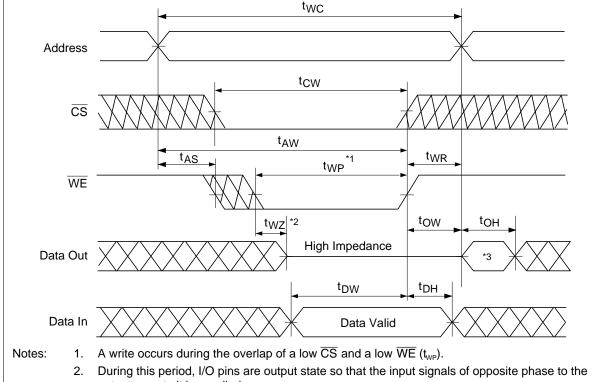
Write Cycle-3 \*1 ( $\overline{OE}$  = Clocked,  $\overline{WE}$  Controlled)



Write Cycle-4 \*1, \*2 ( $\overline{OE}$  = Clocked,  $\overline{CS}$  Controlled)

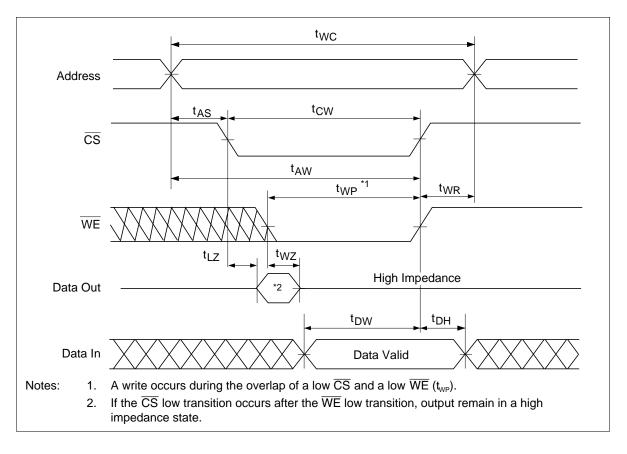


Write Cycle-5 \*1, \*2, \*3 ( $\overline{OE} = L$ ,  $\overline{WE}$  Controlled)



- outputs must nit be applied.
- 3. Output data is the same phase of write data of this write cycle.

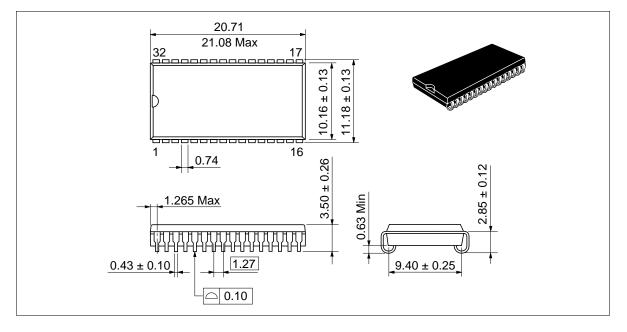
Write Cycle-6 \*1, \*2 ( $\overline{OE} = L$ ,  $\overline{CS}$  Controlled)



### **Package Dimension**

### HM761400HJP Series (CP-32DB)

Unit: mm



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